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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	8MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	66
Program Memory Size	32KB (16K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	902 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17lc766-08-pt

NOTES:

1.0 OVERVIEW

This data sheet covers the PIC17C7XX group of the PIC17CXXX family of microcontrollers. The following devices are discussed in this data sheet:

- PIC17C752
- PIC17C756A
- PIC17C762
- PIC17C766

The PIC17C7XX devices are 68/84-pin, EPROM based members of the versatile PIC17CXXX family of low cost, high performance, CMOS, fully static, 8-bit microcontrollers.

All PIC® microcontrollers employ an advanced RISC architecture. The PIC17CXXX has enhanced core features, 16-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 16-bit wide instruction word with a separate 8-bit wide data path. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 58 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance. For mathematical intensive applications, all devices have a single cycle 8 x 8 Hardware Multiplier.

PIC17CXXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

PIC17C7XX devices have up to 902 bytes of RAM and 66 I/O pins. In addition, the PIC17C7XX adds several peripheral features, useful in many high performance applications, including:

- Four timer/counters
- Four capture inputs
- Three PWM outputs
- Two independent Universal Synchronous Asynchronous Receiver Transmitters (USARTs)
- An A/D converter (multi-channel, 10-bit resolution)
- A Synchronous Serial Port (SPI and I^2C w/ Master mode)

These special features reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption.

There are four oscillator options, of which the single pin RC oscillator provides a low cost solution, the LF oscillator is for low frequency crystals and minimizes power consumption, XT is a standard crystal and the EC is for external clock input.

The SLEEP (power-down) mode offers additional power saving. Wake-up from SLEEP can occur through several external and internal interrupts and device RESETS.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software malfunction.

There are four configuration options for the device operational mode:

- Microprocessor
- Microcontroller
- Extended microcontroller
- Protected microcontroller

The microprocessor and extended microcontroller modes allow up to 64K-words of external program memory.

The device also has Brown-out Reset circuitry. This allows a device RESET to occur if the device V_{DD} falls below the Brown-out voltage trip point (BV_{DD}). The chip will remain in Brown-out Reset until V_{DD} rises above BV_{DD}.

A UV erasable, CERQUAD packaged version (compatible with PLCC), is ideal for code development, while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC17C7XX fits perfectly in applications that require extremely fast execution of complex software programs. These include applications ranging from precise motor control and industrial process control to automotive, instrumentation, and telecom applications.

The EPROM technology makes customization of application programs (with unique security codes, combinations, model numbers, parameter storage, etc.) fast and convenient. Small footprint package options (including die sales) make the PIC17C7XX ideal for applications with space limitations that require high performance.

High speed execution, powerful peripheral features, flexible I/O, and low power consumption all at low cost make the PIC17C7XX ideal for a wide range of embedded control applications.

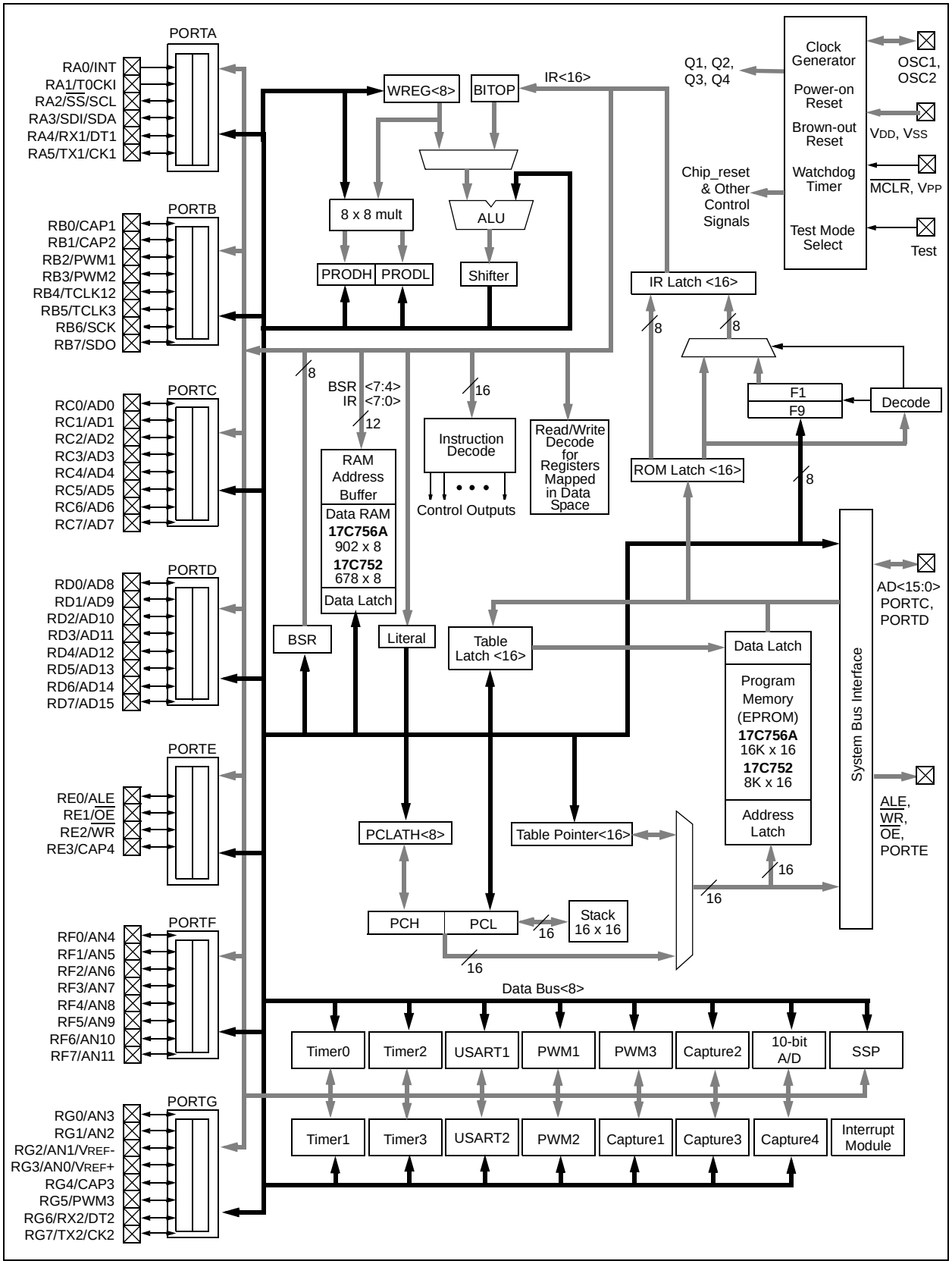
1.1 Family and Upward Compatibility

The PIC17CXXX family of microcontrollers have architectural enhancements over the PIC16C5X and PIC16CXX families. These enhancements allow the device to be more efficient in software and hardware requirements. Refer to Appendix A for a detailed list of enhancements and modifications. Code written for PIC16C5X or PIC16CXX can be easily ported to PIC17CXXX devices (Appendix B).

1.2 Development Support

The PIC17CXXX family is supported by a full featured macro assembler, a software simulator, an in-circuit emulator, a universal programmer, a “C” compiler and fuzzy logic support tools. For additional information, see Section 19.0.

FIGURE 3-1: PIC17C752/756A BLOCK DIAGRAM



4.1.6 RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) and capacitor (C_{EXT}) values, and the operating temperature. In addition to this, oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect oscillation frequency, especially for low C_{EXT} values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 4-7 shows how the R/C combination is connected to the PIC17CXXX. For R_{EXT} values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high R_{EXT} values (e.g. 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep R_{EXT} between 3 kΩ and 100 kΩ.

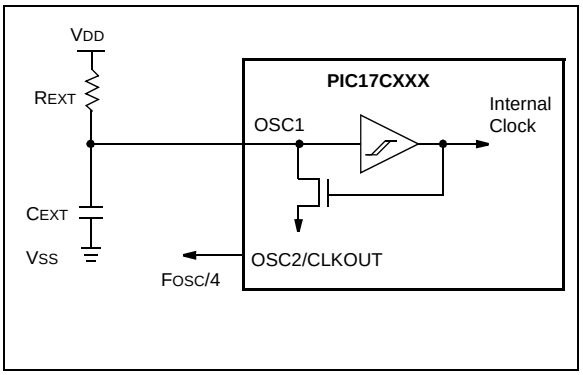
Although the oscillator will operate with no external capacitor (C_{EXT} = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With little or no external capacitance, oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 21.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 21.0 for variation of oscillator frequency due to V_{DD} for given R_{EXT}/C_{EXT} values, as well as frequency variation due to operating temperature for given R, C, and V_{DD} values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin and can be used for test purposes or to synchronize other logic (see Figure 4-8 for waveform).

FIGURE 4-7: RC OSCILLATOR MODE



4.1.6.1 RC Start-up

As the device voltage increases, the RC will immediately start its oscillations once the pin voltage levels meet the input threshold specifications (parameter #D032 and parameter #D042 in the electrical specification section). The time required for the RC to start oscillating depends on many factors. These include:

- Resistor value used
- Capacitor value used
- Device V_{DD} rise time
- System temperature

7.2.2.2 CPU Status Register (CPUSTA)

The CPUSTA register contains the status and control bits for the CPU. This register has a bit that is used to globally enable/disable interrupts. If only a specific interrupt is desired to be enabled/disabled, please refer to the Interrupt Status (INTSTA) register and the Peripheral Interrupt Enable (PIE) registers. The CPUSTA register also indicates if the stack is available and contains the Power-down ($\overline{PD}$) and Time-out ($\overline{TO}$) bits. The $\overline{TO}$, $\overline{PD}$, and STKAV bits are not writable. These bits are set and cleared according to device logic. Therefore, the result of an instruction with the CPUSTA register as destination may be different than intended.

The $\overline{POR}$ bit allows the differentiation between a Power-on Reset, external $\overline{MCLR}$ Reset, or a WDT Reset. The $\overline{BOR}$ bit indicates if a Brown-out Reset occurred.

Note 1:	The $\overline{BOR}$ status bit is a don't care and is not necessarily predictable if the Brown-out circuit is disabled (when the BODEN bit in the Configuration word is programmed).

REGISTER 7-2: CPUSTA REGISTER (ADDRESS: 06h, UNBANKED)

U-0	U-0	R-1	R/W-1	R-1	R-1	R/W-0	R/W-1
—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

bit 7-6 **Unimplemented**: Read as '0'

bit 5 **STKAV**: Stack Available bit
This bit indicates that the 4-bit stack pointer value is Fh, or has rolled over from Fh → 0h (stack overflow).
1 = Stack is available
0 = Stack is full, or a stack overflow may have occurred (once this bit has been cleared by a stack overflow, only a device RESET will set this bit)

bit 4 **GLINTD**: Global Interrupt Disable bit
This bit disables all interrupts. When enabling interrupts, only the sources with their enable bits set can cause an interrupt.
1 = Disable all interrupts
0 = Enables all unmasked interrupts

bit 3 **$\overline{TO}$**: WDT Time-out Status bit
1 = After power-up, by a CLRWDT instruction, or by a SLEEP instruction
0 = A Watchdog Timer time-out occurred

bit 2 **$\overline{PD}$**: Power-down Status bit
1 = After power-up or by the CLRWDT instruction
0 = By execution of the SLEEP instruction

bit 1 **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set by software)

bit 0 **$\overline{BOR}$**: Brown-out Reset Status bit

When BODEN Configuration bit is set (enabled):
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set by software)

When BODEN Configuration bit is clear (disabled):
Don't care

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

7.8 Bank Select Register (BSR)

The BSR is used to switch between banks in the data memory area (Figure 7-9). In the PIC17C7XX devices, the entire byte is implemented. The lower nibble is used to select the peripheral register bank. The upper nibble is used to select the general purpose memory bank.

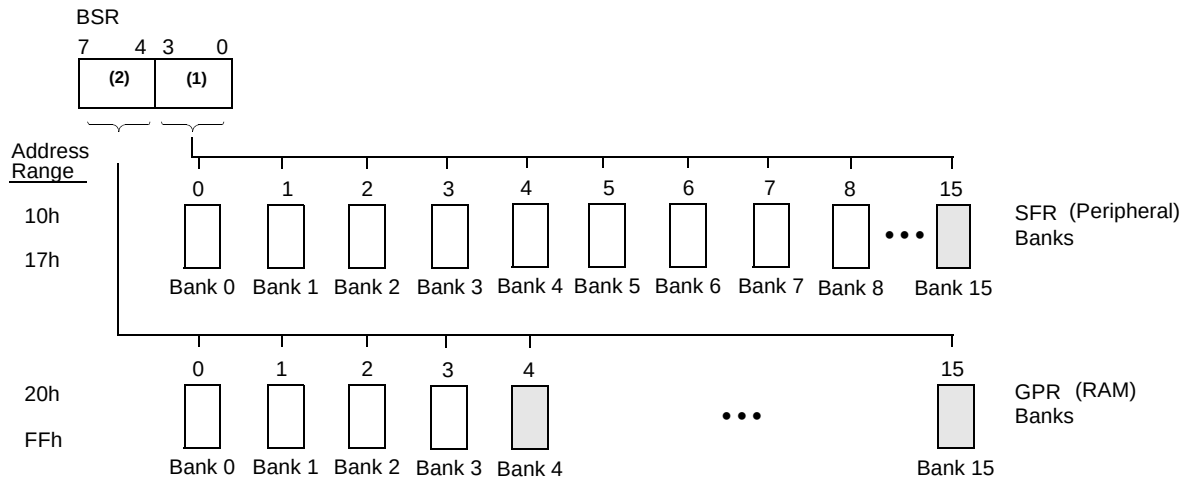
All the Special Function Registers (SFRs) are mapped into the data memory space. In order to accommodate the large number of registers, a banking scheme has been used. A segment of the SFRs, from address 10h to address 17h, is banked. The lower nibble of the bank select register (BSR) selects the currently active “peripheral bank.” Effort has been made to group the peripheral registers of related functionality in one bank. However, it will still be necessary to switch from bank to bank in order to address all peripherals related to a single task. To assist this, a `MOVLB bank` instruction has been included in the instruction set.

The need for a large general purpose memory space dictated a general purpose RAM banking scheme. The upper nibble of the BSR selects the currently active general purpose RAM bank. To assist this, a `MOVLR bank` instruction has been provided in the instruction set.

If the currently selected bank is not implemented (such as Bank 13), any read will read all '0's. Any write is completed to the bit bucket and the ALU status bits will be set/cleared as appropriate.

Note:	Registers in Bank 15 in the Special Function Register area, are reserved for Microchip use. Reading of registers in this bank may cause random values to be read.

FIGURE 7-9: BSR OPERATION

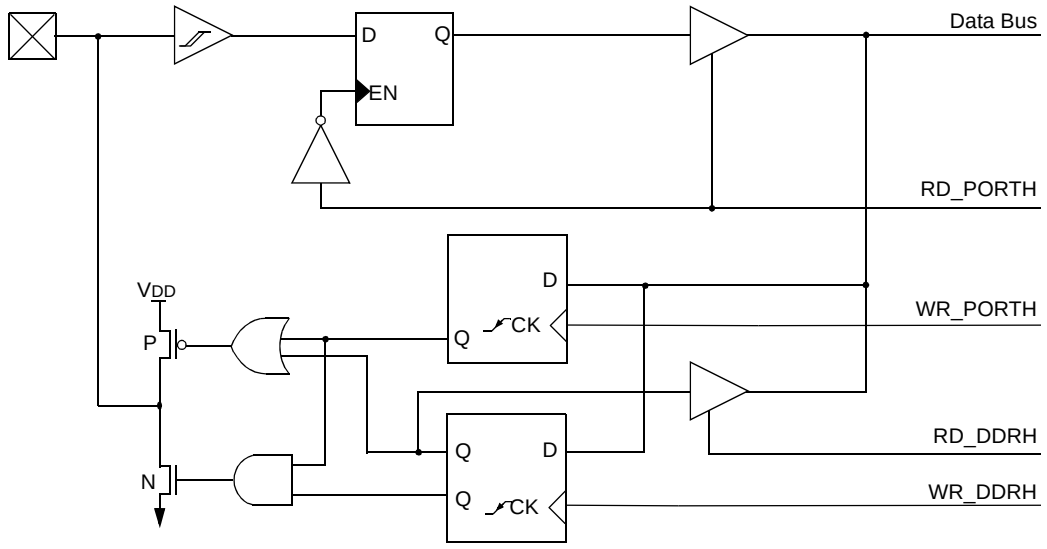


Note 1: For the SFRs only Banks 0 through 8 are implemented. Selection of an unimplemented bank is not recommended. **Bank 15 is reserved for Microchip use, reading of registers in this bank may cause random values to be read.**

2: For the GPRs, Bank 3 is unimplemented on the PIC17C752 and the PIC17C762. Selection of an unimplemented bank is not recommended.

3: SFR Bank 8 is only implemented on the PIC17C76X.

FIGURE 10-18: RH3:RH0 BLOCK DIAGRAM



Note: I/O pins have protection diodes to V_{DD} and V_{SS}.

TABLE 10-15: PORTH FUNCTIONS

Name	Bit	Buffer Type	Function
RH0	bit0	ST	Input/output.
RH1	bit1	ST	Input/output.
RH2	bit2	ST	Input/output.
RH3	bit3	ST	Input/output.
RH4/AN12	bit4	ST	Input/output or analog input 12.
RH5/AN13	bit5	ST	Input/output or analog input 13.
RH6/AN14	bit6	ST	Input/output or analog input 14.
RH7/AN15	bit7	ST	Input/output or analog input 15.

Legend: ST = Schmitt Trigger input

TABLE 10-16: REGISTERS/BITS ASSOCIATED WITH PORTH

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	$\overline{MCLR}$, WDT
10h, Bank 8	DDRH	Data Direction Register for PORTH								1111 1111	1111 1111
11h, Bank 8	PORTH	RH7/AN15	RH6/AN14	RH5/AN13	RH4/AN12	RH3	RH2	RH1	RH0	0000 xxxx	0000 uuuu
15h, Bank 5	ADCON1	ADCS1	ADCS0	ADFM	—	PCFG3	PCFG2	PCFG1	PCFG0	000- 0000	000- 0000

Legend: x = unknown, u = unchanged

13.2 Timer3

Timer3 is a 16-bit timer consisting of the TMR3H and TMR3L registers. TMR3H is the high byte of the timer and TMR3L is the low byte. This timer has an associated 16-bit period register (PR3H/CA1H:PR3L/CA1L). This period register can be software configured to be a another 16-bit capture register.

When the TMR3CS bit (TCON1<2>) is clear, the timer increments every instruction cycle (FOSC/4). When TMR3CS is set, the counter increments on every falling edge of the RB5/TCLK3 pin. In either mode, the TMR3ON bit must be set for the timer/counter to increment. When TMR3ON is clear, the timer will not increment or set flag bit TMR3IF.

Timer3 has two modes of operation, depending on the CA1/PR3 bit (TCON2<3>). These modes are:

- Three capture and one period register mode
- Four capture register mode

The PIC17C7XX has up to four 16-bit capture registers that capture the 16-bit value of TMR3 when events are detected on capture pins. There are four capture pins (RB0/CAP1, RB1/CAP2, RG4/CAP3, and RE3/CAP4), one for each capture register pair. The capture pins are multiplexed with the I/O pins. An event can be:

- A rising edge
- A falling edge
- Every 4th rising edge
- Every 16th rising edge

Each 16-bit capture register has an interrupt flag associated with it. The flag is set when a capture is made. The capture modules are truly part of the Timer3 block. Figure 13-5 and Figure 13-6 show the block diagrams for the two modes of operation.

13.2.1 THREE CAPTURE AND ONE PERIOD REGISTER MODE

In this mode, registers PR3H/CA1H and PR3L/CA1L constitute a 16-bit period register. A block diagram is shown in Figure 13-5. The timer increments until it equals the period register and then resets to 0000h on the next timer clock. TMR3 Interrupt Flag bit (TMR3IF) is set at this point. This interrupt can be disabled by clearing the TMR3 Interrupt Enable bit (TMR3IE). TMR3IF must be cleared in software.

FIGURE 13-5: TIMER3 WITH THREE CAPTURE AND ONE PERIOD REGISTER BLOCK DIAGRAM

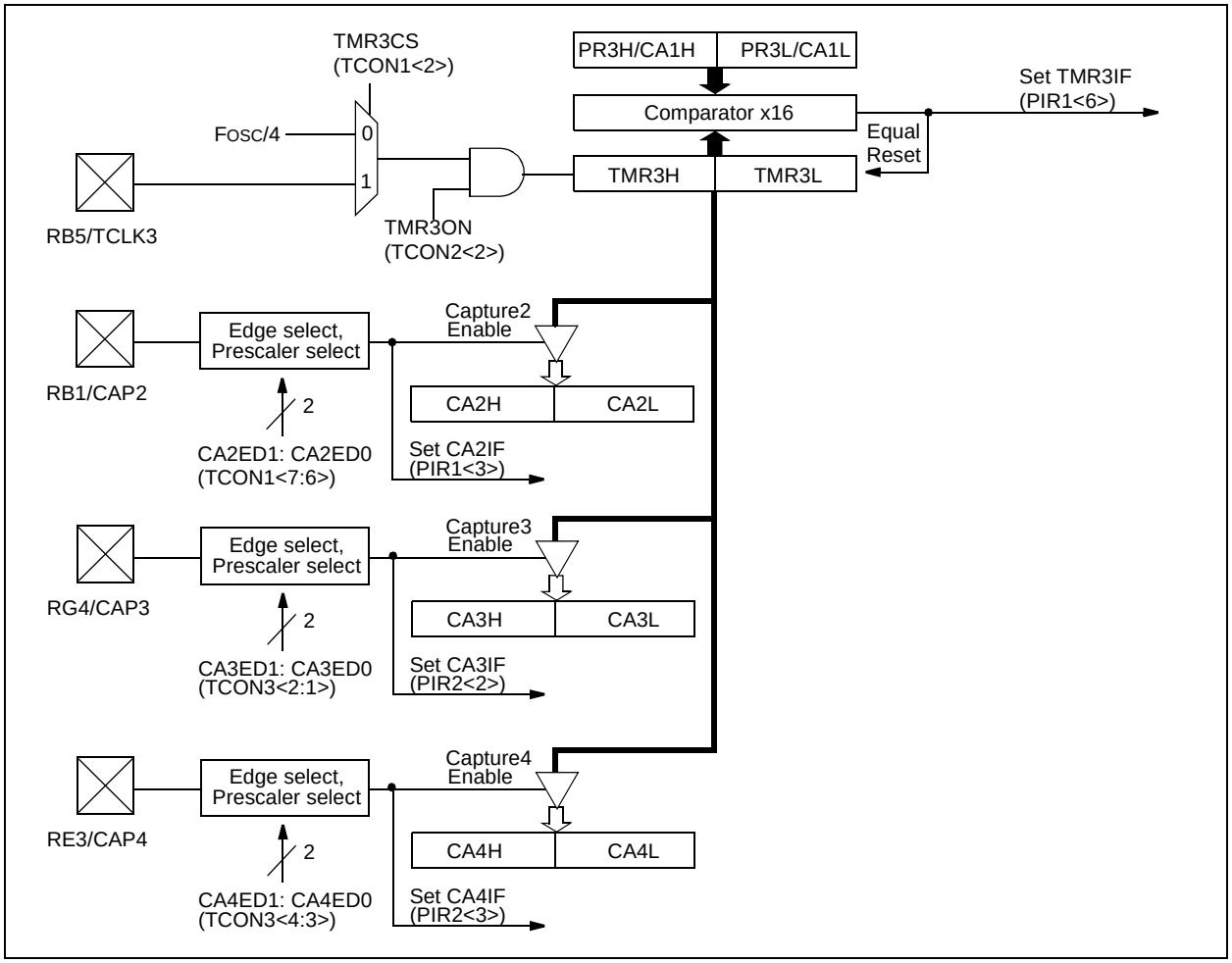


TABLE 14-4: BAUD RATES FOR SYNCHRONOUS MODE

BAUD RATE (K)	FOSC = 33 MHz			FOSC = 25 MHz			FOSC = 20 MHz			FOSC = 16 MHz		
	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)
0.3	NA	—	—	NA	—	—	NA	—	—	NA	—	—
1.2	NA	—	—	NA	—	—	NA	—	—	NA	—	—
2.4	NA	—	—	NA	—	—	NA	—	—	NA	—	—
9.6	NA	—	—	NA	—	—	NA	—	—	NA	—	—
19.2	NA	—	—	NA	—	—	19.53	+1.73	255	19.23	+0.16	207
76.8	77.10	+0.39	106	77.16	+0.47	80	76.92	+0.16	64	76.92	+0.16	51
96	95.93	-0.07	85	96.15	+0.16	64	96.15	+0.16	51	95.24	-0.79	41
300	294.64	-1.79	27	297.62	-0.79	20	294.1	-1.96	16	307.69	+2.56	12
500	485.29	-2.94	16	480.77	-3.85	12	500	0	9	500	0	7
HIGH	8250	—	0	6250	—	0	5000	—	0	4000	—	0
LOW	32.22	—	255	24.41	—	255	19.53	—	255	15.625	—	255

BAUD RATE (K)	FOSC = 10 MHz			FOSC = 7.159 MHz			FOSC = 5.068 MHz		
	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)
0.3	NA	—	—	NA	—	—	NA	—	—
1.2	NA	—	—	NA	—	—	NA	—	—
2.4	NA	—	—	NA	—	—	NA	—	—
9.6	9.766	+1.73	255	9.622	+0.23	185	9.6	0	131
19.2	19.23	+0.16	129	19.24	+0.23	92	19.2	0	65
76.8	75.76	-1.36	32	77.82	+1.32	22	79.2	+3.13	15
96	96.15	+0.16	25	94.20	-1.88	18	97.48	+1.54	12
300	312.5	+4.17	7	298.3	-0.57	5	316.8	+5.60	3
500	500	0	4	NA	—	—	NA	—	—
HIGH	2500	—	0	1789.8	—	0	1267	—	0
LOW	9.766	—	255	6.991	—	255	4.950	—	255

BAUD RATE (K)	FOSC = 3.579 MHz			FOSC = 1 MHz			FOSC = 32.768 kHz		
	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)	KBAUD	%ERROR	SPBRG VALUE (DECIMAL)
0.3	NA	—	—	NA	—	—	0.303	+1.14	26
1.2	NA	—	—	1.202	+0.16	207	1.170	-2.48	6
2.4	NA	—	—	2.404	+0.16	103	NA	—	—
9.6	9.622	+0.23	92	9.615	+0.16	25	NA	—	—
19.2	19.04	-0.83	46	19.24	+0.16	12	NA	—	—
76.8	74.57	-2.90	11	83.34	+8.51	2	NA	—	—
96	99.43	_3.57	8	NA	—	—	NA	—	—
300	298.3	-0.57	2	NA	—	—	NA	—	—
500	NA	—	—	NA	—	—	NA	—	—
HIGH	894.9	—	0	250	—	0	8.192	—	0
LOW	3.496	—	255	0.976	—	255	0.032	—	255

15.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP) MODULE

The Master Synchronous Serial Port (MSSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The MSSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit™ (I^2C)

Figure 15-1 shows a block diagram for the SPI mode, while Figure 15-2 and Figure 15-3 show the block diagrams for the two different I^2C modes of operation.

FIGURE 15-1: SPI MODE BLOCK DIAGRAM

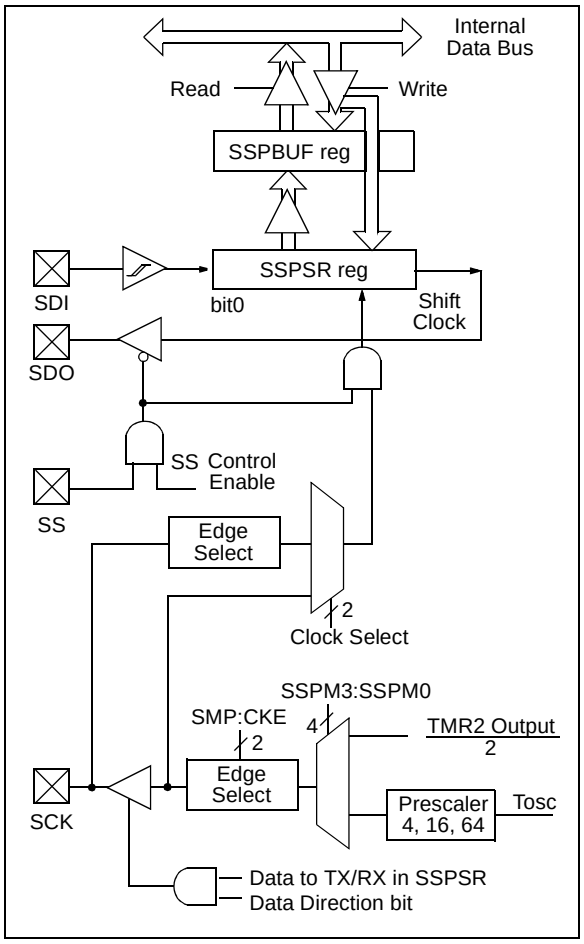


FIGURE 15-2: I^2C SLAVE MODE BLOCK DIAGRAM

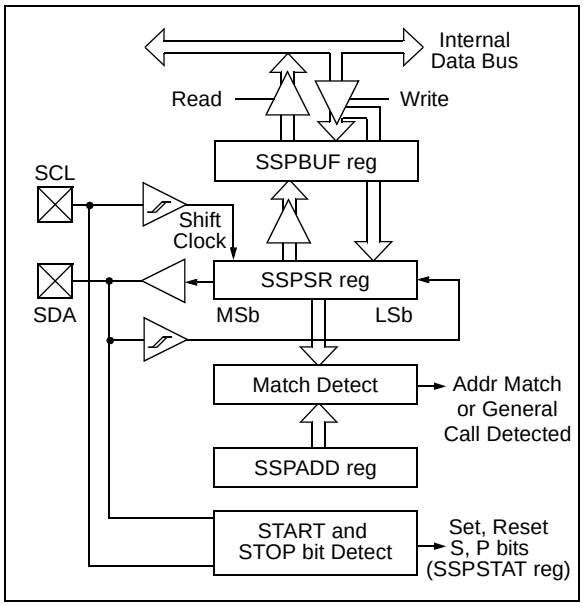
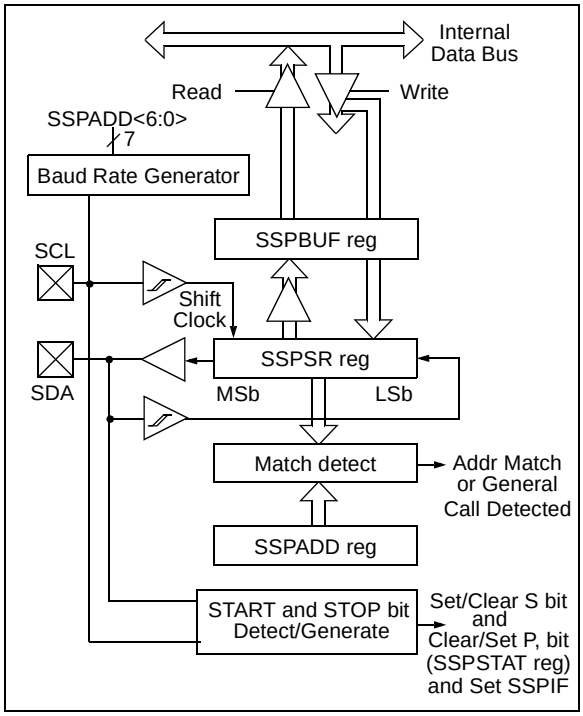


FIGURE 15-3: I^2C MASTER MODE BLOCK DIAGRAM



15.2.1.3 Slave Transmission

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit, and the SCL pin is held low. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then SCL pin should be enabled by setting bit CKP (SSPCON1<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 15-13).

An SSP interrupt is generated for each data transfer byte. The SSPIF flag bit must be cleared in software, and the SSPSTAT register is used to determine the status of the byte transfer. The SSPIF flag bit is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{ACK}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not $\overline{ACK}$), then the data transfer is complete. When the not $\overline{ACK}$ is latched by the slave, the slave logic is reset and the slave then monitors for another occurrence of the START bit. If the SDA line was low ($\overline{ACK}$), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then, the SCL pin should be enabled by setting the CKP bit.

FIGURE 15-12: I²C WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)

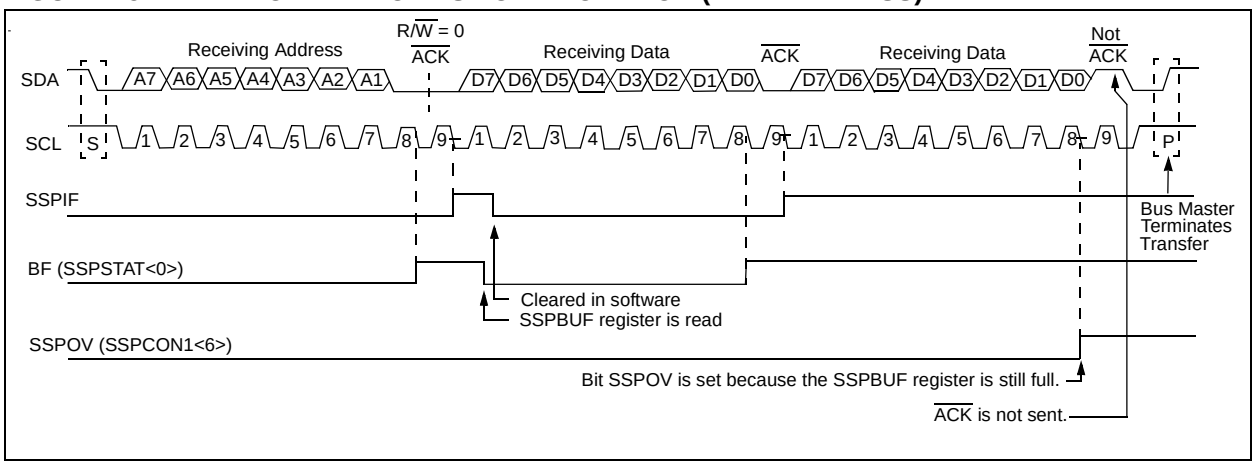
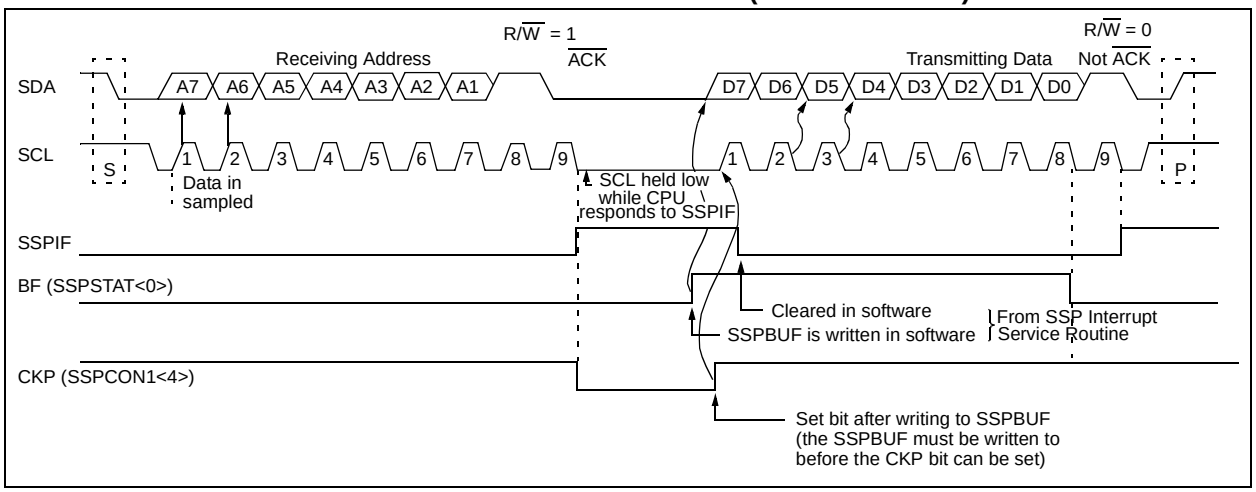


FIGURE 15-13: I²C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)



15.2.5 MASTER MODE

Master mode of operation is supported by interrupt generation on the detection of the START and STOP conditions. The STOP (P) and START (S) bits are cleared from a RESET, or when the MSSP module is disabled. Control of the I^2C bus may be taken when the P bit is set, or the bus is idle, with both the S and P bits clear.

In Master mode, the SCL and SDA lines are manipulated by the MSSP hardware.

The following events will cause SSP Interrupt Flag bit, SSPIF, to be set (SSP Interrupt if enabled):

- START condition
- STOP condition
- Data transfer byte transmitted/received
- Acknowledge transmit
- Repeated Start

FIGURE 15-17: SSP BLOCK DIAGRAM (I^2C MASTER MODE)

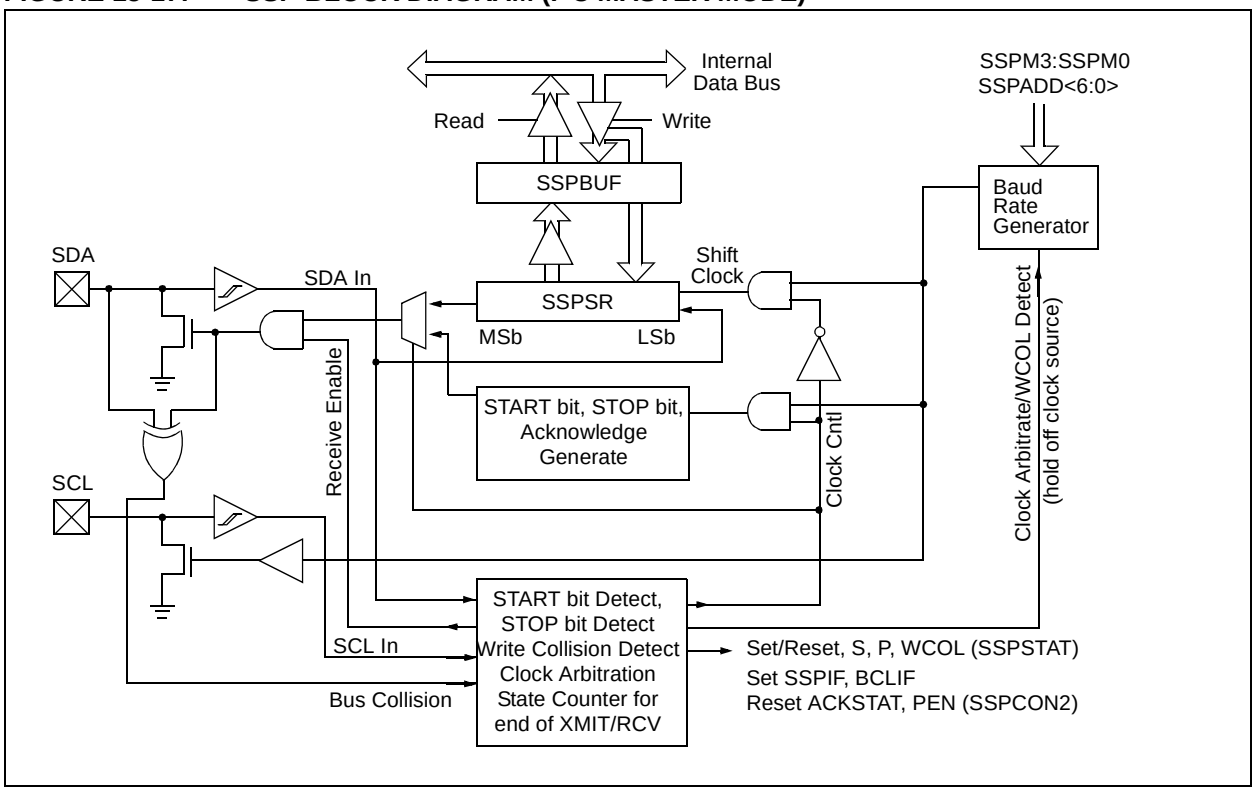
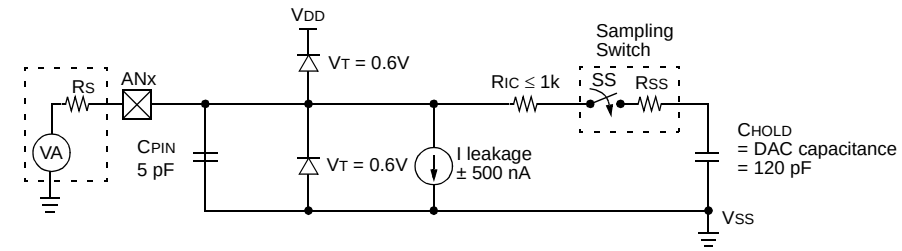
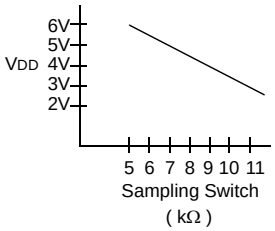


FIGURE 16-3: ANALOG INPUT MODEL



Legend		
	C_{PIN}	= input capacitance
	V_T	= threshold voltage
	I leakage	= leakage current at the pin due to various junctions
	R_{IC}	= interconnect resistance
	SS	= sampling switch
	C_{HOLD}	= sample/hold capacitance (from DAC)



ANDWF **AND WREG with f**

Syntax: [*label*] ANDWF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (WREG) .AND. (f) → (dest)

Status Affected: Z

Encoding:

0000	101d	ffff	ffff

Description: The contents of WREG are AND'ed with register 'f'. If 'd' is 0 the result is stored in WREG. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `ANDWF REG, 1`

Before Instruction
WREG = 0x17
REG = 0xC2

After Instruction
WREG = 0x17
REG = 0x02

BCF **Bit Clear f**

Syntax: [*label*] BCF f,b

Operands: $0 \le f \le 255$
$0 \le b \le 7$

Operation: 0 → (f<b>)

Status Affected: None

Encoding:

1000	1bbb	ffff	ffff

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: `BCF FLAG_REG, 7`

Before Instruction
FLAG_REG = 0xC7

After Instruction
FLAG_REG = 0x47

CALL **Subroutine Call**

Syntax: [*label*] CALL k

Operands: $0 \le k \le 8191$

Operation: PC+ 1→ TOS, k → PC<12:0>, k<12:8> → PCLATH<4:0>; PC<15:13> → PCLATH<7:5>

Status Affected: None

Encoding:

111k	kkkk	kkkk	kkkk

Description: Subroutine call within 8K page. First, return address (PC+1) is pushed onto the stack. The 13-bit value is loaded into PC bits<12:0>. Then the upper-eight bits of the PC are copied into PCLATH. CALL is a two-cycle instruction.

See LCALL for calls outside 8K memory space.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>, Push PC to stack	Process Data	Write to PC
No operation	No operation	No operation	No operation

Example: HERE CALL THERE

Before Instruction
PC = Address (HERE)

After Instruction
PC = Address (THERE)
TOS = Address (HERE + 1)

CLRF **Clear f**

Syntax: [*label*] CLRF f,s

Operands: $0 \le f \le 255$

Operation: 00h → f, $s \in [0,1]$
00h → dest

Status Affected: None

Encoding:

0010	100s	ffff	ffff

Description: Clears the contents of the specified register(s).
s = 0: Data memory location 'f' and WREG are cleared.
s = 1: Data memory location 'f' is cleared.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f' and if specified WREG

Example: CLRF FLAG_REG, 1

Before Instruction
FLAG_REG = 0x5A
WREG = 0x01

After Instruction
FLAG_REG = 0x00
WREG = 0x01

RRNCF **Rotate Right f (no carry)**

Syntax: [*label*] RRNCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

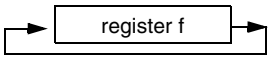
Operation: f<n> → d<n-1>;
f<0> → d<7>

Status Affected: None

Encoding:

0010	000d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the right. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1: `RRNCF REG, 1`

Before Instruction
WREG = ?
REG = 1101 0111

After Instruction
WREG = 0
REG = 1110 1011

Example 2: `RRNCF REG, 0`

Before Instruction
WREG = ?
REG = 1101 0111

After Instruction
WREG = 1110 1011
REG = 1101 0111

SETF **Set f**

Syntax: [*label*] SETF f,s

Operands: $0 \le f \le 255$
$s \in [0,1]$

Operation: FFh → f;
FFh → d

Status Affected: None

Encoding:

0010	101s	ffff	ffff

Description: If 's' is 0, both the data memory location 'f' and WREG are set to FFh. If 's' is 1, only the data memory location 'f' is set to FFh.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f' and other specified register

Example1: `SETF REG, 0`

Before Instruction
REG = 0xDA
WREG = 0x05

After Instruction
REG = 0xFF
WREG = 0xFF

Example2: `SETF REG, 1`

Before Instruction
REG = 0xDA
WREG = 0x05

After Instruction
REG = 0xFF
WREG = 0x05

PIC17LC7XX-08 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
PIC17C7XX-16 (Commercial, Industrial, Extended) **PIC17C7XX-33** (Commercial, Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C for extended -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D010	IDD	**Supply Current (Note 2)**					
		PIC17LC7XX	—	3	6	mA	FOSC = 4 MHz **(Note 4)**
D010		PIC17C7XX	—	3	6	mA	FOSC = 4 MHz **(Note 4)**
D011		PIC17LC7XX	—	5	10	mA	FOSC = 8 MHz
D011		PIC17C7XX	—	5	10	mA	FOSC = 8 MHz
D012			—	9	18	mA	FOSC = 16 MHz
D014		PIC17LC7XX	—	85	150	µA	FOSC = 32 kHz, (EC osc configuration)
D015		PIC17C7XX	—	15	30	mA	FOSC = 33 MHz
D021	IPD	**Power-down Current (Note 3)**					
		PIC17LC7XX	—	<1	5	µA	VDD = 3.0V, WDT disabled
D021 (commercial, industrial)		PIC17C7XX	—	<1	20	µA	VDD = 5.5V, WDT disabled
D021A (extended)			—	2	20	µA	VDD = 5.5V, WDT disabled
		Module Differential Current					
D023	ΔIBOR	BOR circuitry	–	75	150	µA	VDD = 4.5V, BODEN enabled
D024	ΔIWDT	Watchdog Timer	–	10	35	µA	VDD = 5.5V
D026	ΔIAD	A/D converter	–	1	–	µA	VDD = 5.5V, A/D not converting

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD or VSS, T0CKI = VDD, MCLR = VDD; WDT disabled.

Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.

For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD/(2 • R).

For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL • VDD) • f

CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.

The capacitive currents are most significant when the device is configured for external execution (includes Extended Microcontroller mode).

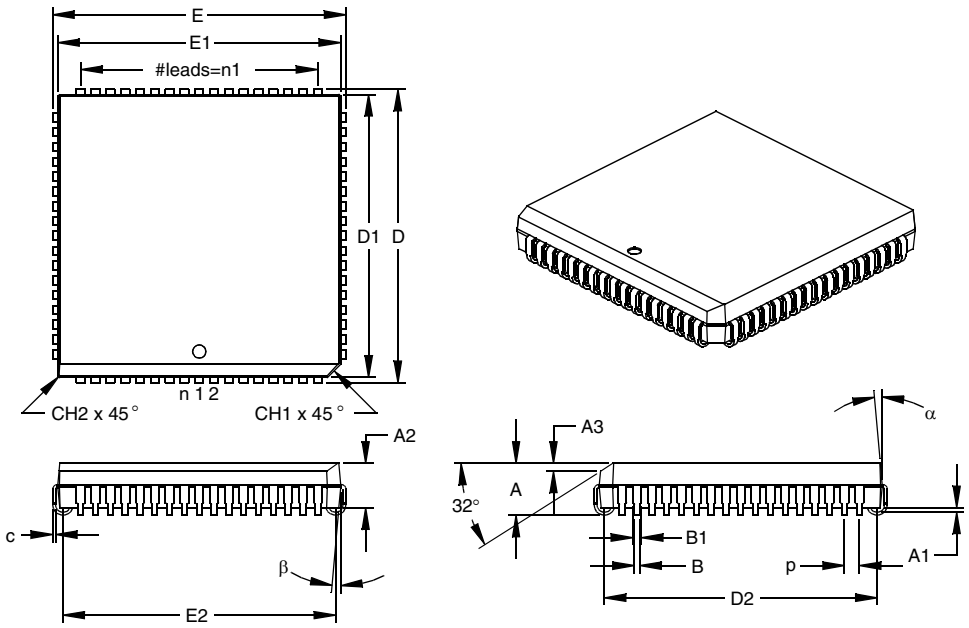
3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula IR = VDD/2REXT (mA) with REXT in kOhm.

5: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device (-16) will operate correctly to this trip point.

68-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		68			68	
Pitch	p		.050			1.27	
Pins per Side	n1		17			17	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.985	.990	.995	25.02	25.15	25.27
Overall Length	D	.985	.990	.995	25.02	25.15	25.27
Molded Package Width	E1	.950	.954	.958	24.13	24.23	24.33
Molded Package Length	D1	.950	.954	.958	24.13	24.23	24.33
Footprint Width	E2	.890	.920	.930	22.61	23.37	23.62
Footprint Length	D2	.890	.920	.930	22.61	23.37	23.62
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-049

